Declaration of Compliance with the REACH

We hereby represent that the products, including the parts and the components consisted thereof, supplied on and after 1st October 2010 by our company conform to the EU REACH (Registration, Evaluation, Authorization and Restriction of Chemicals, EC 1907/2006) and the SVHC (Substances of Very High Concern) chemical substance including Appendix XVII restrictions.

In addition, we declare, to the best of our knowledge, the products comply with the requirements of each of 250 substances which are announced by ECHA as “Substances of Very High Concern (SVHC) on 25th Jun. 2025.

Note:

For ADATA’s products, the SVHC substances of Lead monoxide (Lead oxide) CAS No. 1317-36-8 and 2-Methyl-4'-(methylthio)-2-morpholinopropiophenone CAS No.71868-10-5 or 2-Benzyl-2-(dimethylamino)-4'-morpholinobutyrophenone CAS No.119313-12-1 might contained in raw material(the concentration are over 0.1%), however, the final products (components) will not exist above substance (the concentration are less than 0.1% in the component).

Nick Dai

Nick Dai
Quality Management Division/ Director
Date: 20250626

Substances of Very High Concern (SVHC) contained in the listed article in product.

Product	SVHC Item	CAS No.	Substance Name	Article Location
DRAM Module	98	1317-36-8	Lead monoxide (Lead oxide)	Resistor
	170	80-05-7	4,4’-isopropylidenediphenol(bisphenol A)	Substrate BT material Substrate&PP
	67	127-19-5,	N,N-dimethylacetamide (DMAC)	IC, Inductor
	50	872-50-4	1-Methyl-2-pyrrolidone	IC
	185	7439-92-1	Lead	Resistor Substrate&PP
	203	71868-10-5	2-Methyl-4'-(methylthio)-2-morpholinopropiophenone	Substrate&PP
	98	1317-36-8	Lead monoxide (Lead oxide)	Resistor
SSD	170	80-05-7	4,4’-isopropylidenediphenol(bisphenol A)	Substrate BT material/ Substrate&PP Substrate Core resin/ Substrate Prepreg
	182	556-67-2	Octamethylcyclotetrasiloxane (D4)	Package ink
	183	541-02-6	Decamethylcyclopentasiloxane (D5)	Package ink Silicone: Sealant
	184	540-97-6	Dodecamethylcyclohexasiloxane (D6)	Package ink Silicone: Sealant
	185	7439-92-1	Lead	Resistor Solder ball Substrate&PP/ Substrate Core resin/ Substrate Prepreg
	202	119313-12-1	2-Benzyl-2-(dimethylamino)-4'-morpholinobutyrophenone	photo initiator_substrate Substrate/Substrate solder mask AUS308
	203	71868-10-5	2-Methyl-4'-(methylthio)-2-morpholinopropiophenone	Substrate_Solder mask/ Substrate&PP
	67	127-19-5,	N,N-dimethylacetamide (DMAC)	IC, Inductor
	98	1317-36-8	Lead monoxide (Lead oxide)	Resistor
UFD	170	80-05-7	4,4’-isopropylidenediphenol(bisphenol A)	Substrate BT material/ Substrate&PP Substrate Core resin/ Substrate Prepreg
	185	7439-92-1	Lead	Resistor Substrate&PP
	202	119313-12-1	2-Benzyl-2-(dimethylamino)-4'-morpholinobutyrophenone	Photo initiator_substrate Substrate
	203	71868-10-5	2-Methyl-4'-(methylthio)-2-morpholinopropiophenone	Substrate_Solder mask/ Substrate&PP
	98	1317-36-8	Lead monoxide (Lead oxide)	Resistor R-U & Over coating of CHIP RESISTOR
HDD	170	80-05-7	4,4’-isopropylidenediphenol(bisphenol A)	Substrate&PP
	183	541-02-6	Decamethylcyclopentasiloxane (D5)	Silicone: Sealant
	184	540-97-6	Dodecamethylcyclohexasiloxane (D6)	Silicone: Sealant
	185	7439-92-1	Lead	Resistor
	185	7439-92-1	Lead	Resistor, Substrate&PP solder & Solder flake & Chip & Solder Paste of Diode
	203	71868-10-5	2-Methyl-4'-(methylthio)-2-morpholinopropiophenone	Substrate&PP&Substrate_BT
	170	80-05-7	4,4’-isopropylidenediphenol(bisphenol A)	Substrate
Card	185	7439-92-1	Lead	Resistor
	202	119313-12-1	2-Benzyl-2-(dimethylamino)-4'-morpholinobutyrophenone	Substrate Photo initiator_substrate
	203	71868-10-5	2-Methyl-4'-(methylthio)-2-morpholinopropiophenone	Substrate_Solder mask
	204	71850-09-4	Diisohexyl phthalate	Substrate_Solder mask
	167	1120-71-4	1,3-propanesultone	Electrolyte
Power bank	196	129-00-0; 1718-52-1	Pyrene	Coatings

*The listed table is based on supplier’s response before the date of issue of this declaration.